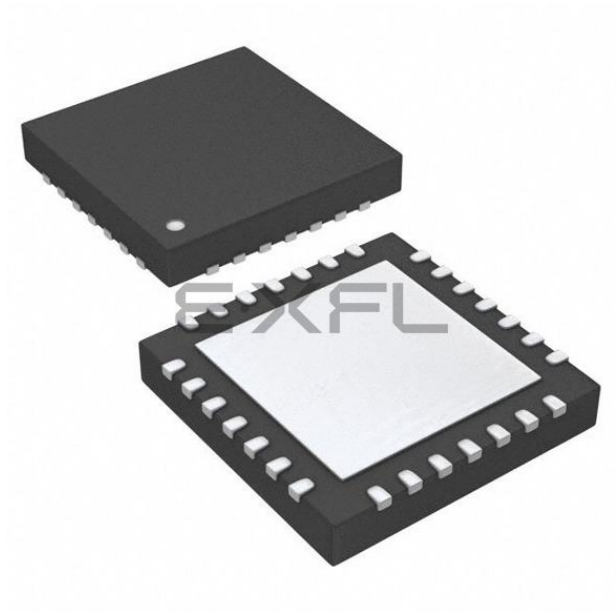

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 11x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-UFQFN Exposed Pad
Supplier Device Package	28-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf723a-i-mv

3.0 RESETS

The PIC16(L)F722A/723A differentiates between various kinds of Reset:

a) Power-on Reset (POR)
b) WDT Reset during normal operation
c) WDT Reset during Sleep
d) $\overline{\text{MCLR}}$ Reset during normal operation
e) $\overline{\text{MCLR}}$ Reset during Sleep
f) Brown-out Reset (BOR)

Some registers are not affected in any Reset condition; their status is unknown on POR and unchanged in any other Reset. Most other registers are reset to a "Reset state" on:

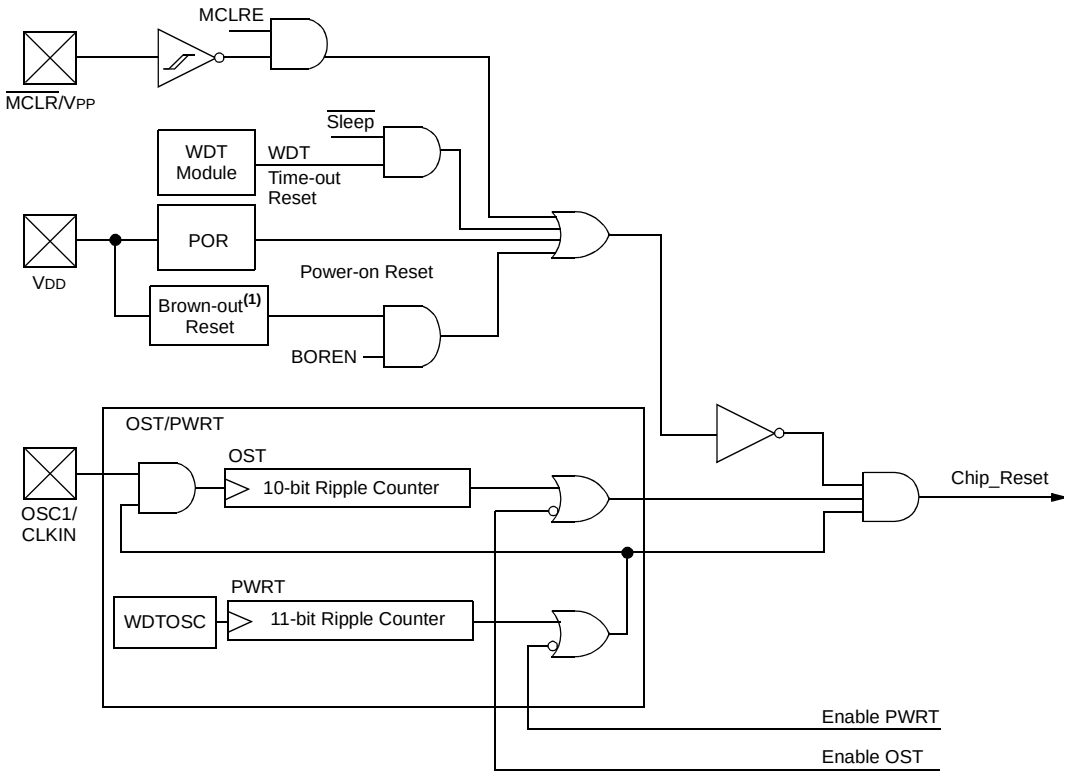
- Power-on Reset (POR)
- $\overline{\text{MCLR}}$ Reset
- $\overline{\text{MCLR}}$ Reset during Sleep
- WDT Reset
- Brown-out Reset (BOR)

Most registers are not affected by a WDT wake-up since this is viewed as the resumption of normal operation. $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared differently in different Reset situations, as indicated in Table 3-3. These bits are used in software to determine the nature of the Reset.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 3-1.

The $\overline{\text{MCLR}}$ Reset path has a noise filter to detect and ignore small pulses. See **Section 23.0 "Electrical Specifications"** for pulse width specifications.

FIGURE 3-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: Refer to the Configuration Word Register 1 (Register 8-1).

3.6 Time-out Sequence

On power-up, the time-out sequence is as follows: first, PWRT time out is invoked after POR has expired, then OST is activated after the PWRT time out has expired. The total time out will vary based on oscillator configuration and $\overline{\text{PWRTE}}$ bit status. For example, in EC mode with $\overline{\text{PWRTE}}$ bit = 1 (PWRT disabled), there will be no time-out at all. Figure 3-4, Figure 3-5 and Figure 3-6 depict time-out sequences.

Since the time outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time-outs will expire. Then, bringing $\overline{\text{MCLR}}$ high will begin execution immediately (see Figure 3-5). This is useful for testing purposes or to synchronize more than one PIC16(L)F722A/723A device operating in parallel.

Table 3-3 shows the Reset conditions for some special registers.

3.7 Power Control (PCON) Register

The Power Control (PCON) register has two Status bits to indicate what type of Reset that last occurred.

Bit 0 is $\overline{\text{BOR}}$ (Brown-out Reset). $\overline{\text{BOR}}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent Resets to see if $\overline{\text{BOR}}$ = 0, indicating that a brown-out has occurred. The $\overline{\text{BOR}}$ Status bit is a “don’t care” and is not necessarily predictable if the brown-out circuit is disabled (BOREN<1:0> = 00 in the Configuration Word register).

Bit 1 is $\overline{\text{POR}}$ (Power-on Reset). It is a ‘0’ on Power-on Reset and unaffected otherwise. The user must write a ‘1’ to this bit following a Power-on Reset. On a subsequent Reset, if $\overline{\text{POR}}$ is ‘0’, it will indicate that a Power-on Reset has occurred (i.e., V_{DD} may have gone too low).

For more information, see **Section 3.5 “Brown-Out Reset (BOR)”**.

TABLE 3-2: TIME OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out Reset		Wake-up from Sleep
	$\overline{\text{PWRTE}}$ = 0	$\overline{\text{PWRTE}}$ = 1	$\overline{\text{PWRTE}}$ = 0	$\overline{\text{PWRTE}}$ = 1	
XT, HS, LP(1)	T_{PWRT} + 1024 • T_{OSC}	1024 • T_{OSC}	T_{PWRT} + 1024 • T_{OSC}	1024 • T_{OSC}	1024 • T_{OSC}
RC, EC, INTOSC	T_{PWRT}	—	T_{PWRT}	—	—

Note 1: LP mode with T1OSC disabled.

TABLE 3-3: RESET BITS AND THEIR SIGNIFICANCE

$\overline{\text{POR}}$	$\overline{\text{BOR}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Condition
0	u	1	1	Power-on Reset
1	0	1	1	Brown-out Reset
u	u	0	u	WDT Reset
u	u	0	0	WDT Wake-up
u	u	u	u	$\overline{\text{MCLR}}$ Reset during normal operation
u	u	1	0	$\overline{\text{MCLR}}$ Reset during Sleep

Legend: u = unchanged, x = unknown

TABLE 3-4: INITIALIZATION CONDITION FOR REGISTERS (CONTINUED)

Register	Address	Power-on Reset/ Brown-out Reset(1)	$\overline{\text{MCLR}}$ Reset/ WDT Reset	Wake-up from Sleep through Interrupt/Time out
PIE1	8Ch	0000 0000	0000 0000	uuuu uuuu
PIE2	8Dh	---- ---0	---- ---0	---- ---u
PCON	8Eh	---- --qq	---- --uu(1,5)	---- --uu
T1GCON	8Fh	0000 0x00	uuuu uxuu	uuuu uxuu
OSCCON	90h	--10 qq--	--10 qq--	--uu qq--
OSCTUNE	91h	--00 0000	--uu uuuu	--uu uuuu
PR2	92h	1111 1111	1111 1111	uuuu uuuu
SSPADD	93h	0000 0000	0000 0000	uuuu uuuu
SSPMSK	93h	1111 1111	1111 1111	uuuu uuuu
SSPSTAT	94h	0000 0000	0000 0000	uuuu uuuu
WPUB	95h	1111 1111	1111 1111	uuuu uuuu
IOCB	96h	0000 0000	0000 0000	uuuu uuuu
TXSTA	98h	0000 -010	0000 -010	uuuu -uuu
SPBRG	99h	0000 0000	0000 0000	uuuu uuuu
APFCON	9Ch	---- --00	---- --00	---- --uu
FVRCON	9Dh	q000 --00	q000 --00	uuuu --uu
ADCON1	9Fh	-000 --00	-000 --00	-uuu --uu
CPSCON0	108h	0--- 0000	0--- 0000	u--- uuuu
CPSCON1	109h	---- 0000	---- 0000	---- uuuu
PMDATL	10Ch	xxxx xxxx	xxxx xxxx	uuuu uuuu
PMADRL	10Dh	xxxx xxxx	xxxx xxxx	uuuu uuuu
PMDATH	10Eh	--xx xxxx	--xx xxxx	--uu uuuu
PMADRH	10Fh	---x xxxx	---x xxxx	---u uuuu
ANSELA	185h	--11 1111	--11 1111	--uu uuuu
ANSELB	186h	--11 1111	--11 1111	--uu uuuu
PMCON1	18Ch	1--- ---0	1--- ---0	u--- ---u

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0', q = value depends on condition.

Note 1: If VDD goes too low, Power-on Reset will be activated and registers will be affected differently.

2: One or more bits in INTCON and/or PIR1 and PIR2 will be affected (to cause wake-up).

3: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

4: See Table 3-5 for Reset value for specific condition.

5: If Reset was due to brown-out, then bit 0 = 0. All other Resets will cause bit 0 = u.

6.4 PORTC and TRISC Registers

PORTC is a 8-bit wide, bidirectional port. The corresponding data direction register is TRISC (Register 6-11). Setting a TRISC bit (= 1) will make the corresponding PORTC pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISC bit (= 0) will make the corresponding PORTC pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). Example 6-3 shows how to initialize PORTC.

Reading the PORTC register (Register 6-10) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch.

The TRISC register (Register 6-11) controls the PORTC pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISC register are maintained set when using them as analog inputs. I/O pins configured as analog input always read '0'.

EXAMPLE 6-3: INITIALIZING PORTC

```
BANKSEL PORTC        ;
CLRF    PORTC        ;Init PORTC
BANKSEL TRISC        ;
MOVLW   B'00001100'  ;Set RC<3:2> as inputs
MOVWF   TRISC        ;and set RC<7:4,1:0>
                     ;as outputs
```

The location of the CCP2 function is controlled by the CCP2SEL bit in the APFCON register (refer to Register 6-1).

REGISTER 6-10: PORTC: PORTC REGISTER

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **RC<7:0>**: PORTC General Purpose I/O Pin bits
1 = Port pin is > V_{IH}
0 = Port pin is < V_{IL}

REGISTER 6-11: TRISC: PORTC TRI-STATE REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **TRISC<7:0>:** PORTC Tri-State Control bits
1 = PORTC pin configured as an input (tri-stated)
0 = PORTC pin configured as an output

14.5 Software Control

The software portion of the capacitive sensing module is required to determine the change in frequency of the capacitive sensing oscillator. This is accomplished by the following:

- Setting a fixed-time base to acquire counts on Timer0 or Timer1
- Establishing the nominal frequency for the capacitive sensing oscillator
- Establishing the reduced frequency for the capacitive sensing oscillator due to an additional capacitive load
- Set the frequency threshold

14.5.1 NOMINAL FREQUENCY (NO CAPACITIVE LOAD)

To determine the nominal frequency of the capacitive sensing oscillator:

- Remove any extra capacitive load on the selected CPSx pin
- At the start of the fixed-time base, clear the timer resource
- At the end of the fixed-time base, save the value in the timer resource

The value of the timer resource is the number of oscillations of the capacitive sensing oscillator for the given time base. The frequency of the capacitive sensing oscillator is equal to the number of counts on in the timer divided by the period of the fixed-time base.

14.5.2 REDUCED FREQUENCY (ADDITIONAL CAPACITIVE LOAD)

The extra capacitive load will cause the frequency of the capacitive sensing oscillator to decrease. To determine the reduced frequency of the capacitive sensing oscillator:

- Add a typical capacitive load on the selected CPSx pin
- Use the same fixed-time base as the nominal frequency measurement
- At the start of the fixed-time base, clear the timer resource
- At the end of the fixed-time base, save the value in the timer resource

The value of the timer resource is the number of oscillations of the capacitive sensing oscillator with an additional capacitive load. The frequency of the capacitive sensing oscillator is equal to the number of counts on in the timer divided by the period of the fixed-time base. This frequency should be less than the value obtained during the nominal frequency measurement.

14.5.3 FREQUENCY THRESHOLD

The frequency threshold should be placed midway between the value of nominal frequency and the reduced frequency of the capacitive sensing oscillator. Refer to Application Note *AN1103, Software Handling for Capacitive Sensing* (DS01103) for more detailed information the software required for capacitive sensing module.

Note:	For more information on general capacitive sensing refer to Application Notes: •*AN1101, Introduction to Capacitive Sensing* (DS01101) •*AN1102, Layout and Physical Design Guidelines for Capacitive Sensing* (DS01102)

14.6 Operation During Sleep

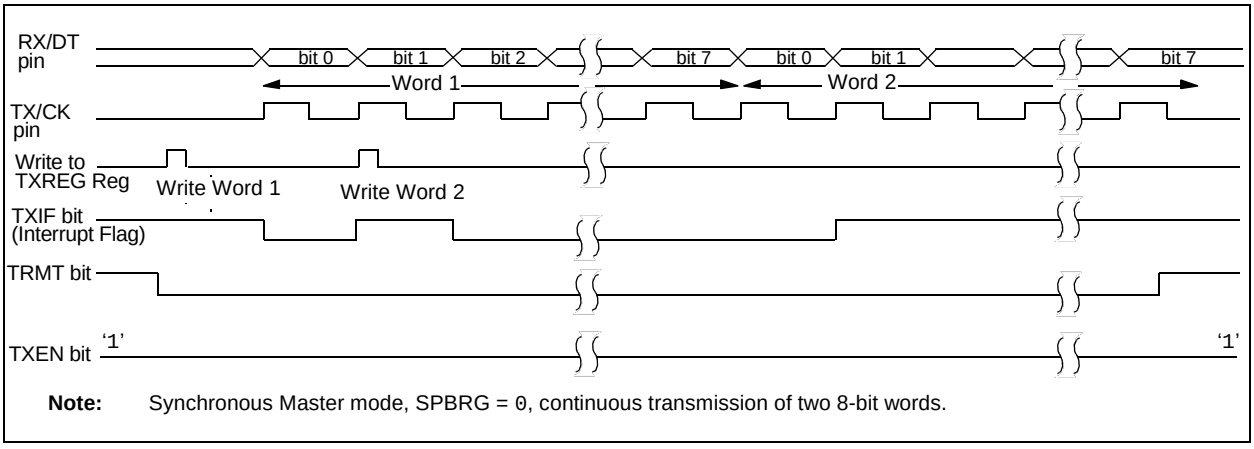
The capacitive sensing oscillator will continue to run as long as the module is enabled, independent of the part being in Sleep. In order for the software to determine if a frequency change has occurred, the part must be awake. However, the part does not have to be awake when the timer resource is acquiring counts. One way to acquire the Timer1 counts while in Sleep is to have Timer1 gated with the overflow of the Watchdog Timer. This can be accomplished using the following steps:

1. Configure the Watchdog Time-out overflow as the Timer1's gate source T1GSS<1:0> = 11.
2. Set Timer1 gate to toggle mode by setting the T1GTM bit of the T1GCON register.
3. Set the TMR1GE bit of the T1GCON register.
4. Set TMR1ON bit of the T1CON register.
5. Enable capacitive sensing module with the appropriate current settings and pin selection.
6. Clear Timer1.
7. Put the part to Sleep.
8. On the first WDT overflow, the capacitive sensing oscillator will begin to increment Timer1. Then put the part to Sleep.
9. On the second WDT overflow Timer1 will stop incrementing. Then run the software routine to determine if a frequency change has occurred.

Refer to **Section 12.0 "Timer1 Module with Gate Control"** for additional information.

Note 1:	When using the WDT to set the interval on Timer1, any other source that wakes the part up early will cause the WDT overflow to be delayed, affecting the value captured by Timer1.
2:	Timer0 does not operate when in Sleep, and therefore cannot be used for capacitive sense measurements in Sleep.

FIGURE 16-6: SYNCHRONOUS TRANSMISSION



Note: Synchronous Master mode, SPBRG = 0, continuous transmission of two 8-bit words.

FIGURE 16-7: SYNCHRONOUS TRANSMISSION (THROUGH TXEN)

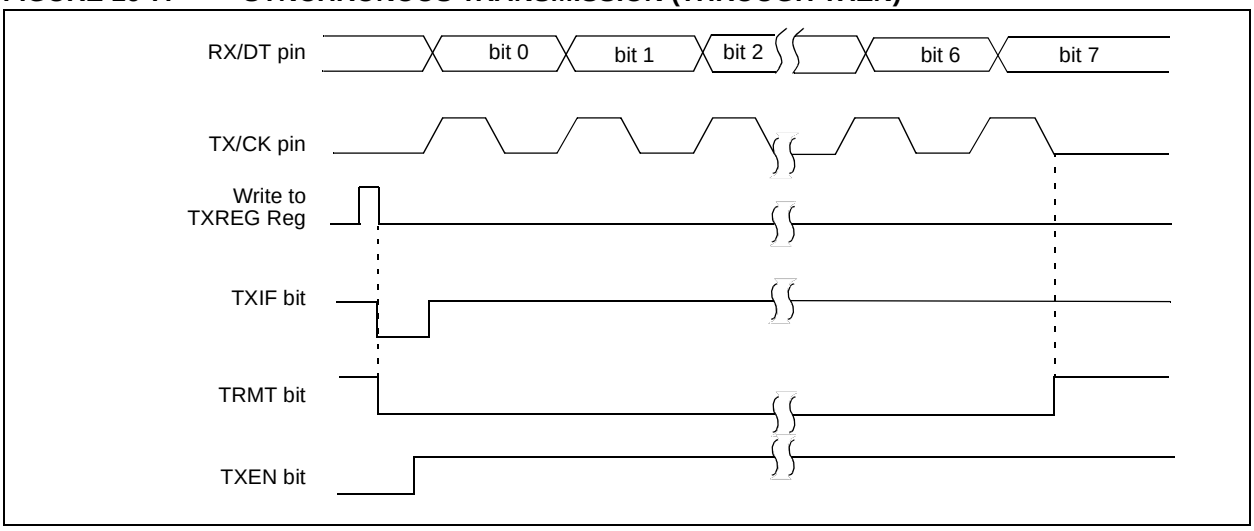


TABLE 16-6: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
SPBRG	BRG7	BRG6	BRG5	BRG4	BRG3	BRG2	BRG1	BRG0	0000 0000	0000 0000
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111
TXREG	AUSART Transmit Data Register								0000 0000	0000 0000
TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used for synchronous master transmission.

16.3.1.4 Synchronous Master Reception

Data is received at the RX/DT pin. The RX/DT pin output driver is automatically disabled when the AUSART is configured for synchronous master receive operation.

In Synchronous mode, reception is enabled by setting either the Single Receive Enable bit (SREN of the RCSTA register) or the Continuous Receive Enable bit (CREN of the RCSTA register).

When SREN is set and CREN is clear, only as many clock cycles are generated as there are data bits in a single character. The SREN bit is automatically cleared at the completion of one character. When CREN is set, clocks are continuously generated until CREN is cleared. If CREN is cleared in the middle of a character the CK clock stops immediately and the partial character is discarded. If SREN and CREN are both set, then SREN is cleared at the completion of the first character and CREN takes precedence.

To initiate reception, set either SREN or CREN. Data is sampled at the RX/DT pin on the trailing edge of the TX/CK clock pin and is shifted into the Receive Shift Register (RSR). When a complete character is received into the RSR, the RCIF bit of the PIR1 register is set and the character is automatically transferred to the two character receive FIFO. The Least Significant eight bits of the top character in the receive FIFO are available in RCREG. The RCIF bit remains set as long as there are un-read characters in the receive FIFO.

16.3.1.5 Slave Clock

Synchronous data transfers use a separate clock line, which is synchronous with the data. A device configured as a slave receives the clock on the TX/CK line. The TX/CK pin output driver is automatically disabled when the device is configured for synchronous slave transmit or receive operation. Serial data bits change on the leading edge to ensure they are valid at the trailing edge of each clock. One data bit is transferred for each clock cycle. Only as many clock cycles should be received as there are data bits.

16.3.1.6 Receive Overrun Error

The receive FIFO buffer can hold two characters. An overrun error will be generated if a third character, in its entirety, is received before RCREG is read to access the FIFO. When this happens the OERR bit of the RCSTA register is set. Previous data in the FIFO will not be overwritten. The two characters in the FIFO buffer can be read, however, no additional characters will be received until the error is cleared. The OERR bit can only be cleared by clearing the overrun condition. If the overrun error occurred when the SREN bit is set and CREN is clear then the error is cleared by reading RCREG. If the overrun occurred when the CREN bit is set then the error condition is cleared by either clearing the CREN bit of the RCSTA register.

16.3.1.7 Receiving 9-bit Characters

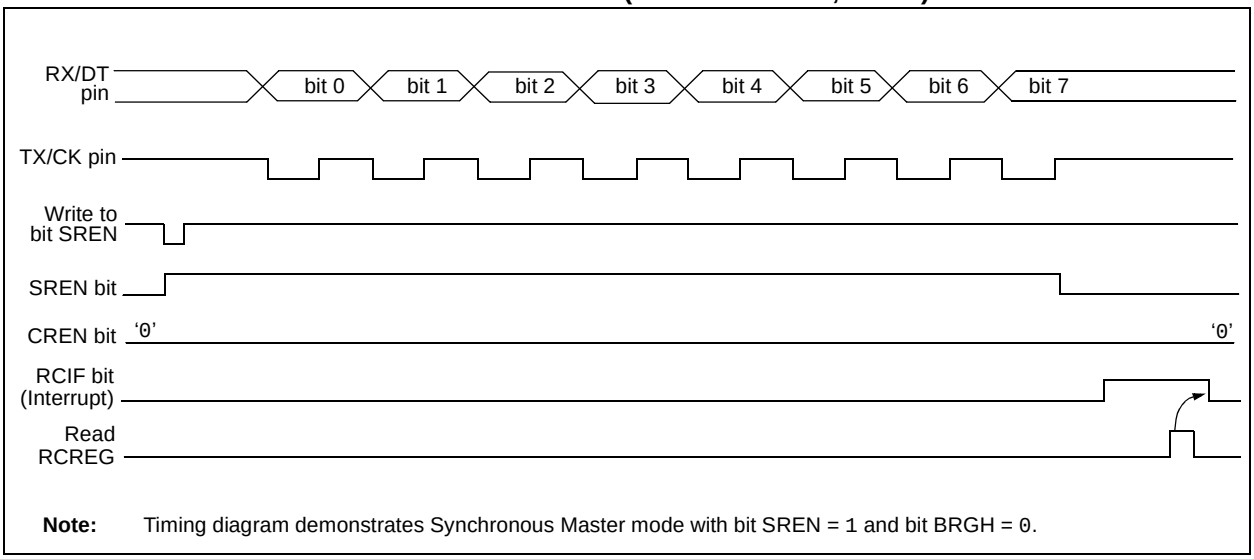
The AUSART supports 9-bit character reception. When the RX9 bit of the RCSTA register is set, the AUSART will shift nine bits into the RSR for each character received. The RX9D bit of the RCSTA register is the ninth, and Most Significant, data bit of the top unread character in the receive FIFO. When reading 9-bit data from the receive FIFO buffer, the RX9D data bit must be read before reading the eight Least Significant bits from the RCREG.

Address detection in Synchronous modes is not supported, therefore the ADDEN bit of the RCSTA register must be cleared.

16.3.1.8 Synchronous Master Reception Setup:

1. Initialize the SPBRG register for the appropriate baud rate. Set or clear the BRGH bit, as required, to achieve the desired baud rate.
2. Enable the synchronous master serial port by setting bits SYNC, SPEN and CSRC.
3. Ensure bits CREN and SREN are clear.
4. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
5. If 9-bit reception is desired, set bit RX9.
6. Verify address detection is disabled by clearing the ADDEN bit of the RCSTA register.
7. Start reception by setting the SREN bit or for continuous reception, set the CREN bit.
8. Interrupt flag bit RCIF of the PIR1 register will be set when reception of a character is complete. An interrupt will be generated if the RCIE interrupt enable bit of the PIE1 register was set.
9. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
10. Read the 8-bit received data by reading the RCREG register.
11. If an overrun error occurs, clear the error by either clearing the CREN bit of the RCSTA register or by clearing the SPEN bit, which resets the AUSART.

FIGURE 16-8: SYNCHRONOUS RECEPTION (MASTER MODE, SREN)



Note: Timing diagram demonstrates Synchronous Master mode with bit SREN = 1 and bit BRGH = 0.

TABLE 16-7: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
RCREG	AUSART Receive Data Register								0000 0000	0000 0000
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000X	0000 000X
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111
TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used for synchronous master reception.

FIGURE 17-4: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 0)

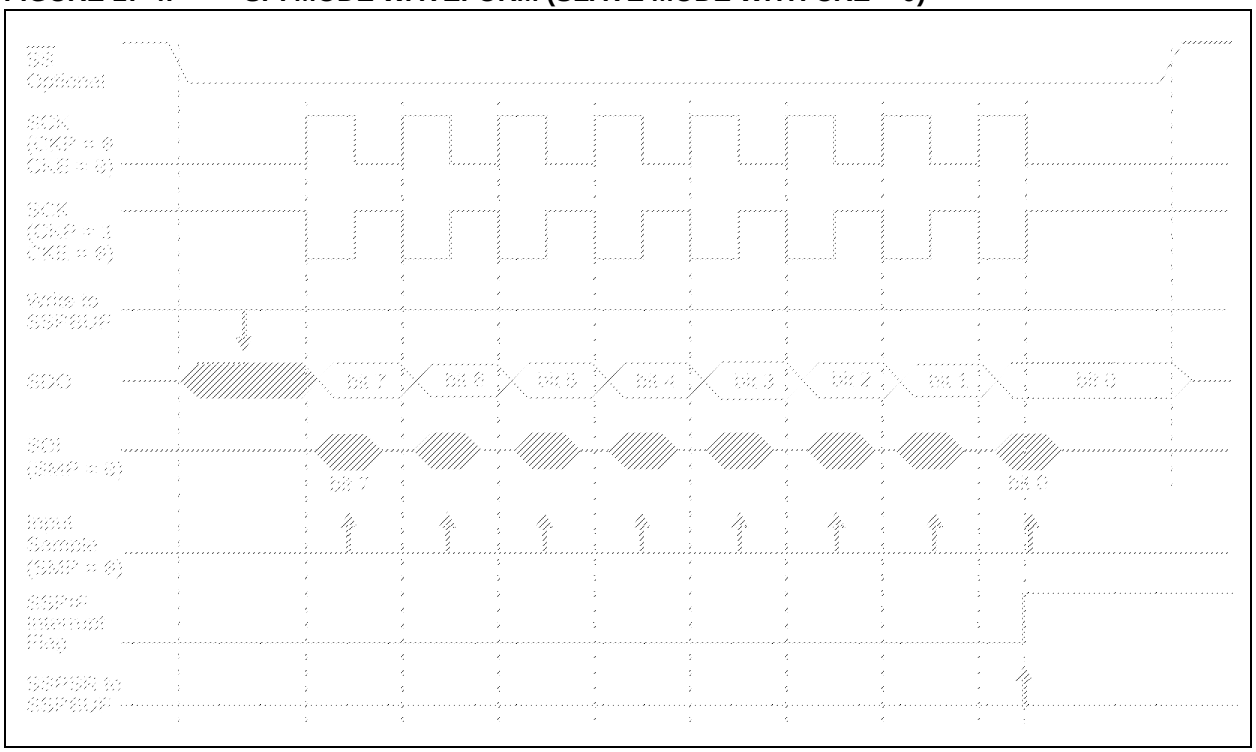
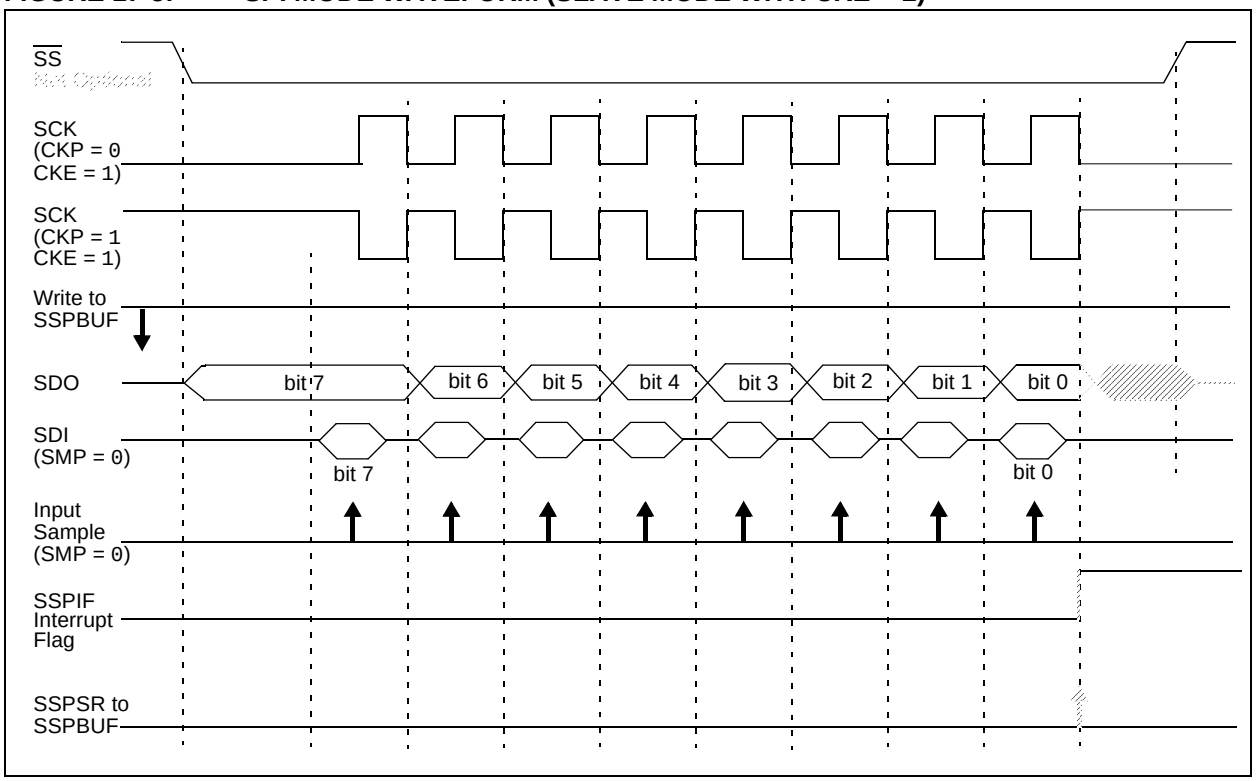


FIGURE 17-5: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 1)



REGISTER 18-1: PMCON1: PROGRAM MEMORY CONTROL 1 REGISTER

R-1	U-0	U-0	U-0	U-0	U-0	U-0	R/S-0
Reserved	—	—I	—	—	—	—	RD
bit 7							bit 0

Legend:		S = Setable bit, cleared in hardware	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **Reserved:** Read as ‘1’. Maintain this bit set.

bit 6-1 **Unimplemented:** Read as ‘0’

bit 0 **RD:** Read Control bit

1 = Initiates an program memory read (The RD is cleared in hardware; the RD bit can only be set (not cleared) in software).

0 = Does not initiate a program memory read

REGISTER 18-2: PMDATH: PROGRAM MEMORY DATA HIGH REGISTER

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	PMD13	PMD12	PMD11	PMD10	PMD9	PMD8
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **PMD<13:8>:** The value of the program memory word pointed to by PMADRH and PMADRL after a Program Memory Read command.

REGISTER 18-3: PMDATL: PROGRAM MEMORY DATA LOW REGISTER

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
PMD7	PMD6	PMD5	PMD4	PMD3	PMD2	PMD1	PMD0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-0 **PMD<7:0>:** The value of the program memory word pointed to by PMADRH and PMADRL after a Program Memory Read command.

20.0 IN-CIRCUIT SERIAL PROGRAMMING™ (ICSP™)

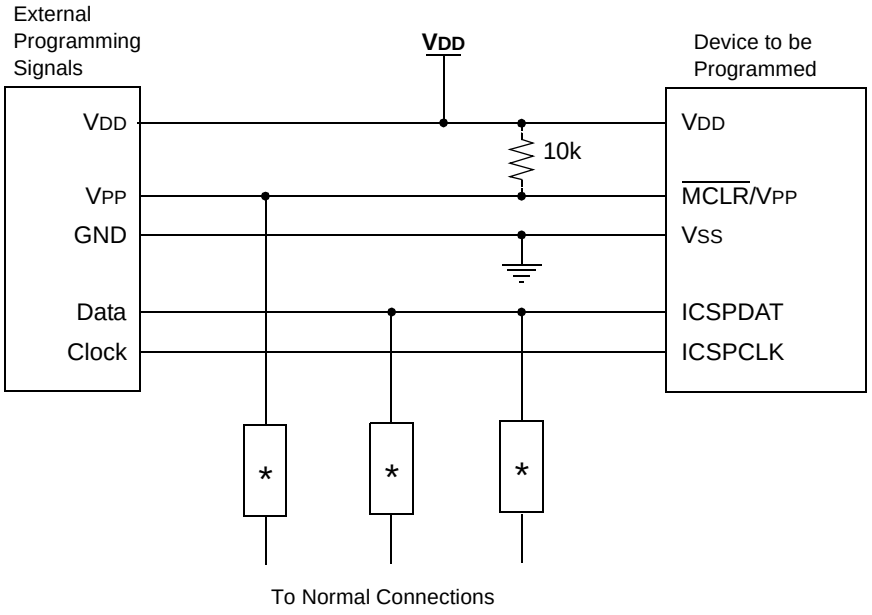
ICSP™ programming allows customers to manufacture circuit boards with unprogrammed devices. Programming can be done after the assembly process allowing the device to be programmed with the most recent firmware or a custom firmware. Five pins are needed for ICSP™ programming:

- ICSPCLK
- ICSPDAT
- MCLR/VPP
- VDD
- VSS

The device is placed into Program/Verify mode by holding the ICSPCLK and ICSPDAT pins low then raising the voltage on MCLR/VPP from 0v to VPP. In Program/Verify mode the Program Memory, User IDs and the Configuration Words are programmed through serial communications. The ICSPDAT pin is a bidirectional I/O used for transferring the serial data and the ISCPCLK pin is the clock input. For more information on ICSP™ refer to the *"PIC16(L)F72X Memory Programming Specification"* (DS41332).

Note:	The ICD 2 produces a VPP voltage greater than the maximum VPP specification of the PIC16(L)F722A/723A. When using this programmer, an external circuit, such as the AC164112 MPLAB ICD 2 VPP voltage limiter, is required to keep the VPP voltage within the device specifications.

FIGURE 20-1: TYPICAL CONNECTION FOR ICSP™ PROGRAMMING



* Isolation devices (as required).

23.1 DC Characteristics: PIC16(L)F722A/723A-I/E (Industrial, Extended)

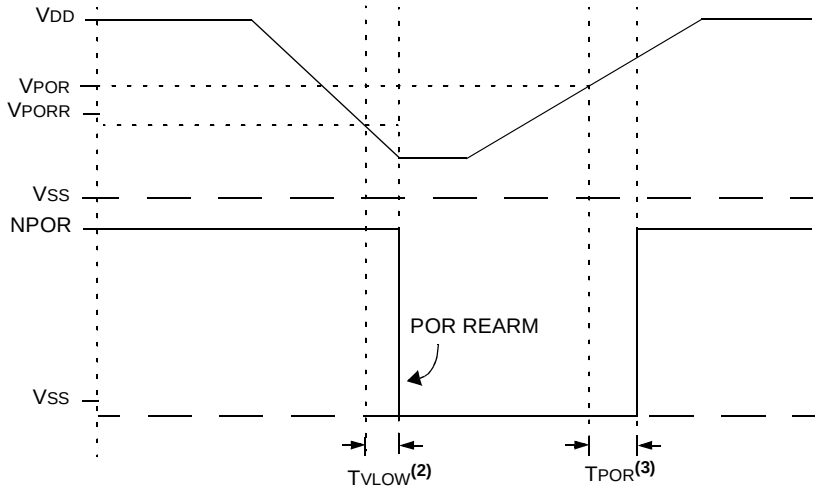
PIC16LF722A/723A			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
PIC16F722A/723A			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**					
		PIC16LF722A/723A	1.8 1.8 2.3 2.5	— — — —	3.6 3.6 3.6 3.6	V V V V	FOSC ≤ 16 MHz: HFINTOSC, EC FOSC ≤ 4 MHz FOSC ≤ 20 MHz, EC FOSC ≤ 20 MHz, HS
D001		**PIC16F722A/723A**	1.8 1.8 2.3 2.5	— — — —	5.5 5.5 5.5 5.5	V V V V	FOSC ≤ 16 MHz: HFINTOSC, EC FOSC ≤ 4 MHz FOSC ≤ 20 MHz, EC FOSC ≤ 20 MHz, HS
D002*	VDR	**RAM Data Retention Voltage(1)**					
		PIC16LF722A/723A	1.5	—	—	V	Device in Sleep mode
D002*		**PIC16F722A/723A**	1.7	—	—	V	Device in Sleep mode
	VPOR*	**Power-on Reset Release Voltage**	—	1.6	—	V	
	VPORR*	**Power-on Reset Rearm Voltage**					
		PIC16LF722A/723A	—	0.8	—	V	Device in Sleep mode
		PIC16F722A/723A	—	1.7	—	V	Device in Sleep mode
D003	VFVR	**Fixed Voltage Reference Voltage, Initial Accuracy**	-5.5 -5.5 -5.5	— — —	5.5 5.5 5.5	% % %	VFVR = 1.024V, VDD ≥ 2.5V VFVR = 2.048V, VDD ≥ 2.5V VFVR = 4.096V, VDD ≥ 4.75V; -40 ≤ TA ≤ 85°C
			-6 -6 -6	— — —	6 6 6	% % %	VFVR = 1.024V, VDD ≥ 2.5V VFVR = 2.048V, VDD ≥ 2.5V VFVR = 4.096V, VDD ≥ 4.75V; -40 ≤ TA ≤ 125°C
D004*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	See **Section 3.2 "Power-on Reset (POR)"** for details.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

FIGURE 23-1: POR AND POR REARM WITH SLOW RISING VDD



Note 1: When NPOR is low, the device is held in Reset.
2: TPOR 1 μs typical.
3: TVLOW 2.7 μs typical.

23.3 DC Characteristics: PIC16(L)F722A/723A-I/E (Power-Down) (Continued)

PIC16LF722A/723A			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
PIC16F722A/723A			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							VDD	Note
	Power-down Base Current (IPD)(2)							
D027		—	0.06	0.7	5.0	µA	1.8	A/D Current **(Note 1, Note 4)**, no conversion in progress
		—	0.08	1.0	5.5	µA	3.0	
D027		—	6	10.7	18	µA	1.8	A/D Current **(Note 1, Note 4)**, no conversion in progress
		—	7	10.6	20	µA	3.0	
		—	7.2	11.9	22	µA	5.0	
D027A		—	250	400	—	µA	1.8	A/D Current **(Note 1, Note 4)**, conversion in progress
		—	250	400	—	µA	3.0	
D027A		—	280	430	—	µA	1.8	A/D Current **(Note 1, Note 4, Note 5)**, conversion in progress
		—	280	430	—	µA	3.0	
		—	280	430	—	µA	5.0	
D028		—	2.2	3.2	14.4	µA	1.8	Cap Sense Low Power Oscillator mode
		—	3.3	4.4	15.6	µA	3.0	
D028		—	6.5	13	21	µA	1.8	Cap Sense Low Power Oscillator mode
		—	8	14	23	µA	3.0	
		—	8	14	25	µA	5.0	
D028A		—	4.2	6	17	µA	1.8	Cap Sense Medium Power Oscillator mode
		—	6	7	18	µA	3.0	
D028A		—	8.5	15.5	23	µA	1.8	Cap Sense Medium Power Oscillator mode
		—	11	17	24	µA	3.0	
		—	11	18	27	µA	5.0	
D028B		—	12	14	25	µA	1.8	Cap Sense High Power Oscillator mode
		—	32	35	44	µA	3.0	
D028B		—	16	20	31	µA	1.8	Cap Sense High Power Oscillator mode
		—	36	41	50	µA	3.0	
		—	42	49	58	µA	5.0	

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base IDD or IPD current from this limit. Max values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD.

3: Fixed Voltage Reference is automatically enabled whenever the BOR is enabled.

4: A/D oscillator source is FRC.

5: 0.1 µF capacitor on VCAP (RA0).

23.4 DC Characteristics: PIC16(L)F722A/723A-I/E

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O PORT:					
D030		with TTL buffer	—	—	0.8	V	4.5V ≤ VDD ≤ 5.5V
D030A			—	—	0.15 VDD	V	1.8V ≤ VDD ≤ 4.5V
D031		with Schmitt Trigger buffer	—	—	0.2 VDD	V	2.0V ≤ VDD ≤ 5.5V
		with I2C levels	—	—	0.3 VDD	V	
D032		$\overline{MCLR}$, OSC1 (RC mode)(1)	—	—	0.2 VDD	V	
D033A		OSC1 (HS mode)	—	—	0.3 VDD	V	
	VIH	**Input High Voltage**					
		I/O ports:		—	—		
D040		with TTL buffer	2.0	—	—	V	4.5V ≤ VDD ≤ 5.5V
D040A			0.25 VDD + 0.8	—	—	V	1.8V ≤ VDD ≤ 4.5V
D041		with Schmitt Trigger buffer	0.8 VDD	—	—	V	2.0V ≤ VDD ≤ 5.5V
		with I2C levels	0.7 VDD	—	—	V	
D042		$\overline{MCLR}$	0.8 VDD	—	—	V	
D043A		OSC1 (HS mode)	0.7 VDD	—	—	V	
D043B		OSC1 (RC mode)	0.9 VDD	—	—	V	**(Note 1)**
	IIL	**Input Leakage Current(2)**					
D060		I/O ports	—	± 5	± 125	nA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance, 85°C
				± 5	± 1000	nA	125°C
D061		$\overline{MCLR}$(3)	—	± 50	± 200	nA	VSS ≤ VPIN ≤ VDD, 85°C
	IPUR	**PORTB Weak Pull-up Current**					
D070*			25 25	100 140	200 300	 μA	VDD = 3.3V, VPIN = VSS VDD = 5.0V, VPIN = VSS
	VOL	**Output Low Voltage(4)**					
D080		I/O ports	—	—	0.6	V	IOL = 8 mA, VDD = 5V IOL = 6 mA, VDD = 3.3V IOL = 1.8 mA, VDD = 1.8V
	VOH	**Output High Voltage(4)**					
D090		I/O ports	VDD - 0.7	—	—	V	IOH = 3.5 mA, VDD = 5V IOH = 3 mA, VDD = 3.3V IOH = 1 mA, VDD = 1.8V
		Capacitive Loading Specs on Output Pins					
D101*	COSC2	OSC2 pin	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1
D101A*	CIO	All I/O pins	—	—	50	pF	
		Program Flash Memory					

Legend: TBD = To Be Determined

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended to use an external clock in RC mode.

2: Negative current is defined as current sourced by the pin.

3: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

4: Including OSC2 in CLKOUT mode.

23.5 Thermal Considerations

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C					
Param No.	**Sym.**	**Characteristic**	**Typ.**	**Units**	**Conditions**
TH01	θJA	Thermal Resistance Junction to Ambient	60.0	°C/W	28-pin SPDIP package
			69.7	°C/W	28-pin SOIC package
			71.0	°C/W	28-pin SSOP package
			52.5	°C/W	28-pin UQFN 4x4mm package
			30.0	°C/W	28-pin QFN 6x6mm package
TH02	θJC	Thermal Resistance Junction to Case	29.0	°C/W	28-pin SPDIP package
			18.9	°C/W	28-pin SOIC package
			24.0	°C/W	28-pin SSOP package
			16.7	°C/W	28-pin UQFN 4x4mm package
			5.0	°C/W	28-pin QFN 6x6mm package
TH03	TJMAX	Maximum Junction Temperature	150	°C	
TH04	PD	Power Dissipation	—	W	PD = PINTERNAL + PI/O
TH05	PINTERNAL	Internal Power Dissipation	—	W	PINTERNAL = IDD x VDD(1)
TH06	PI/O	I/O Power Dissipation	—	W	PI/O = Σ (IOL * VOL) + Σ (IOH * (VDD - VOH))
TH07	PDER	Derated Power	—	W	PDER = PDMAX (TJ - TA)/θJA(2)

Note 1: IDD is current to run the chip alone without driving any load on the output pins.
2: TA = Ambient Temperature
3: TJ = Junction Temperature

FIGURE 24-38: PIC16LF722A/723A CAP SENSE MEDIUM POWER IPD vs. VDD

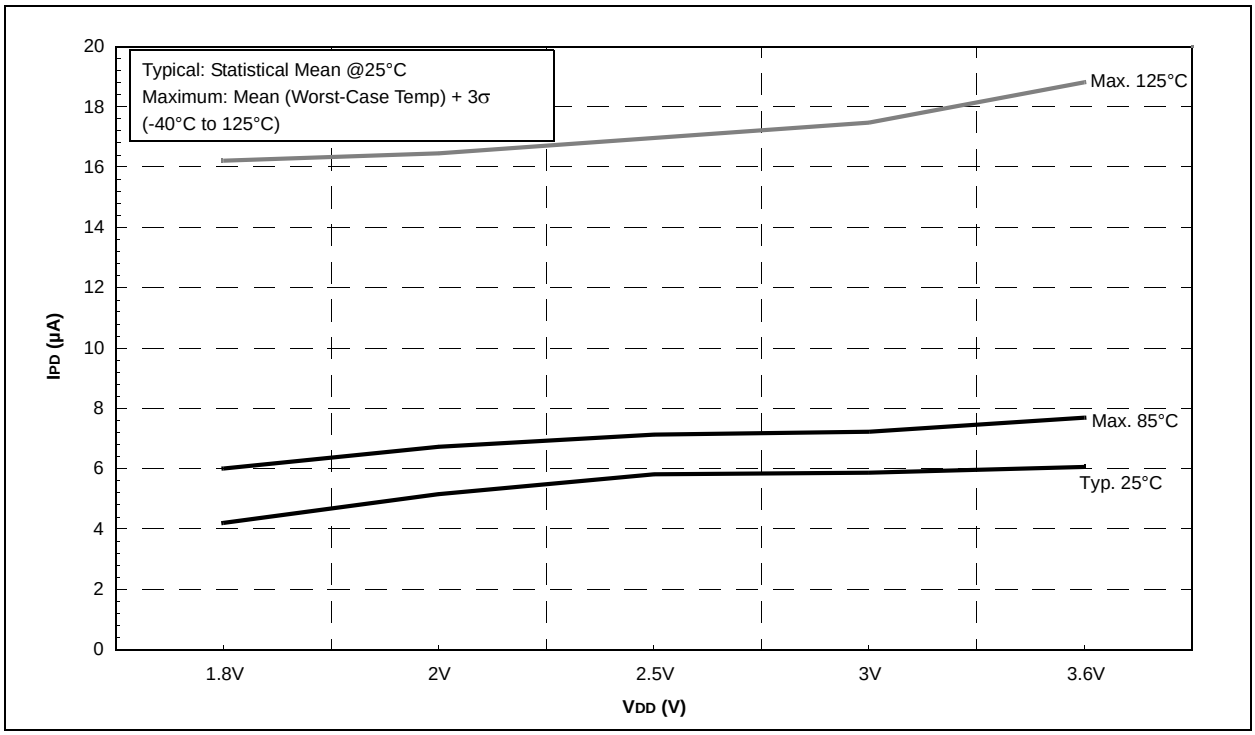


FIGURE 24-39: PIC16F722A/723A CAP SENSE LOW POWER IPD vs. VDD, VCAP = 0.1µF

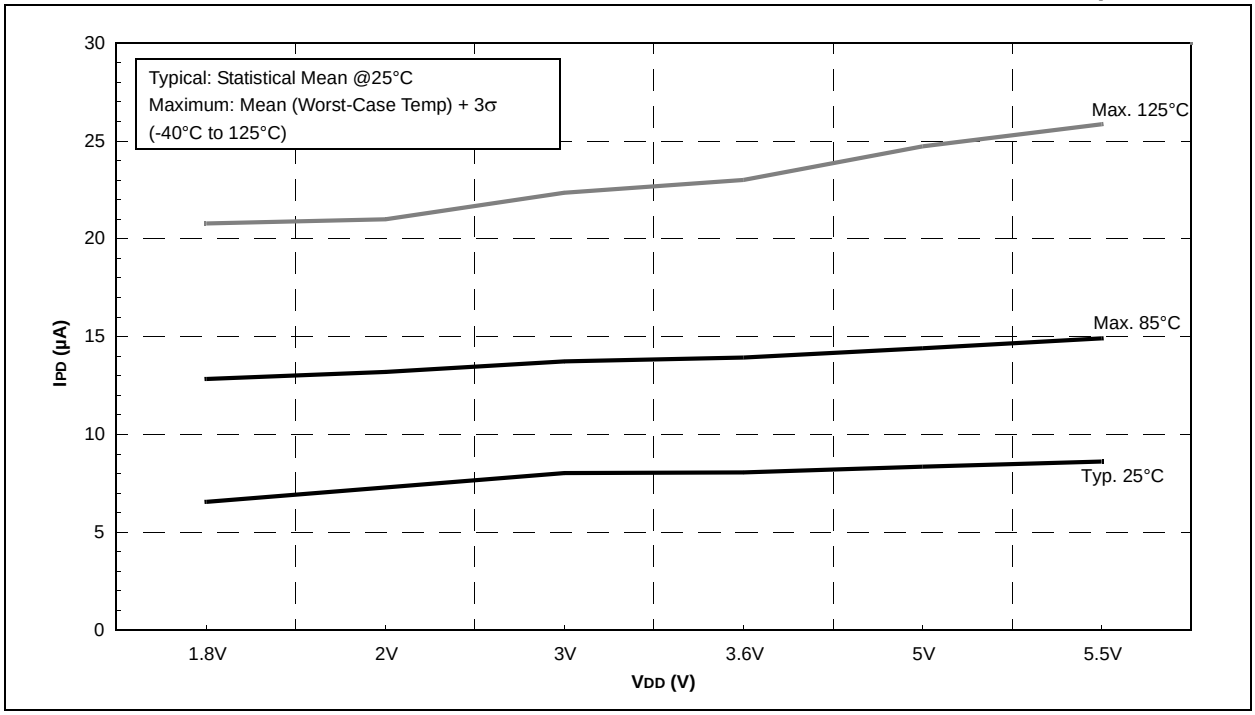


FIGURE 24-50: SCHMITT TRIGGER INPUT THRESHOLD VIN vs. VDD OVER TEMPERATURE

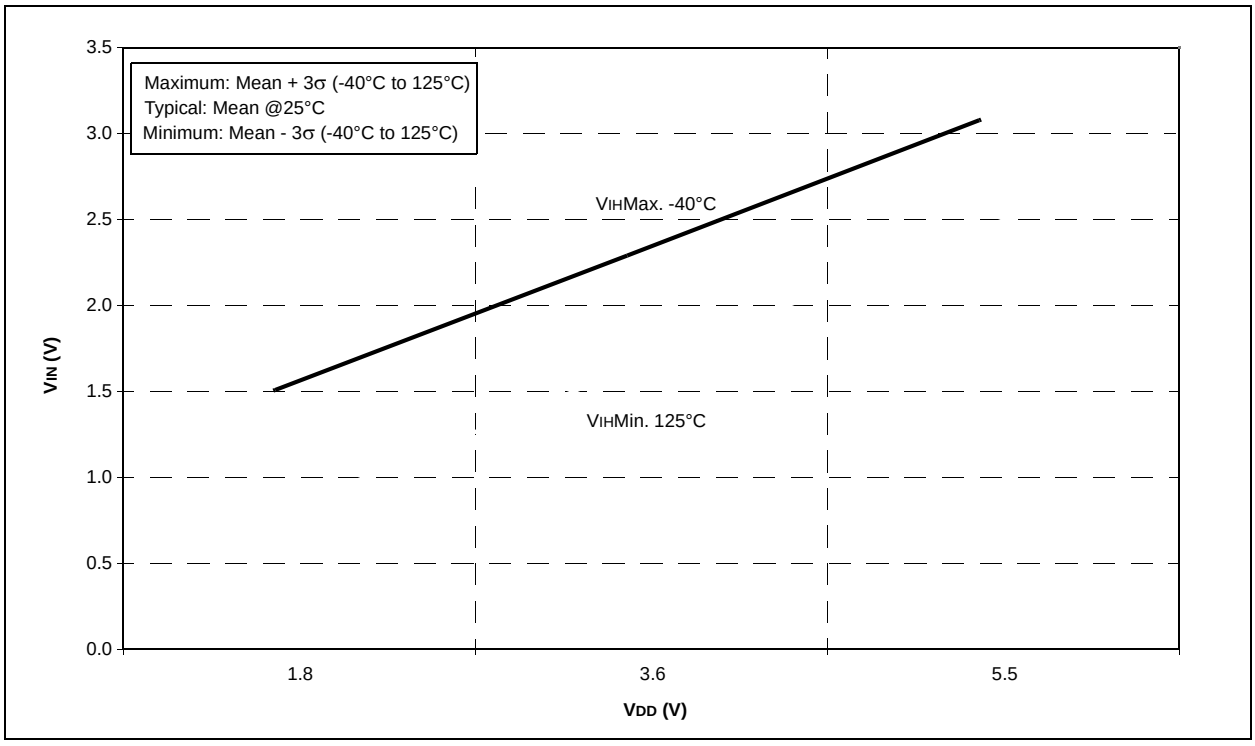
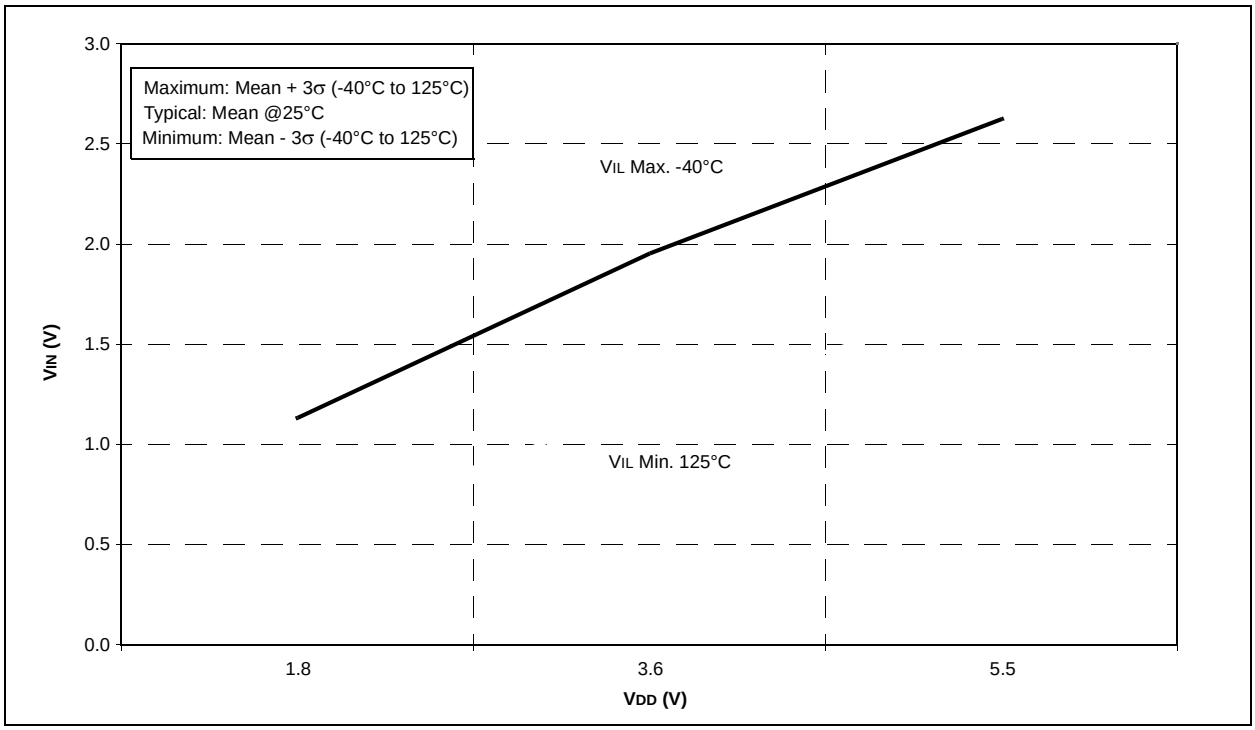
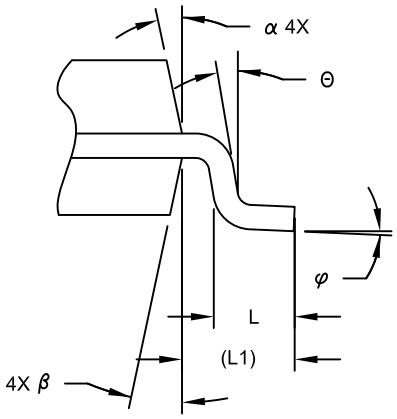


FIGURE 24-51: SCHMITT TRIGGER INPUT THRESHOLD VIN vs. VDD OVER TEMPERATURE

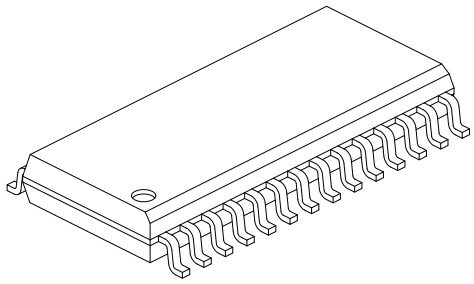


28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2